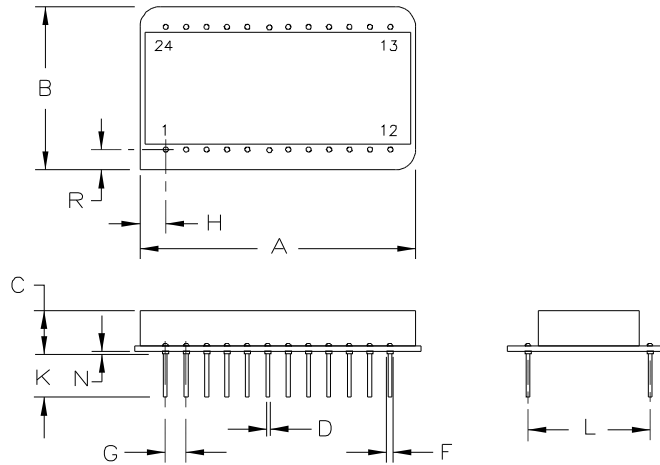


Package Number 075 - 24-Pin



DIM	INCHES		MILLIMETERS		N O E	DIM	INCHES		MILLIMETERS		N O E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	1.310	1.360	33.27	34.54							
B	.770	.810	19.56	20.57							
C	.150	.210	3.81	5.33							
D	.018	.021	0.46	0.53							
F	.035	.050	0.89	1.27							
G	.100	BASIC	2.54	BASIC							
H	.110	.130	2.79	3.30							
K	.150	.250	3.81	6.35							
L	.600	BASIC	15.24	BASIC							
N	.002	.010	0.05	0.25							
R	.085	.105	2.16	2.67							

NOTES:
 1. LEADS IN TRUE POSITION WITHIN .010" (.25mm) R @ MMC AT SEATING PLANE.
 2. PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.

PACKAGE NUMBER: ZZ075 REV.: A
 JEDEC NUMBER: NONE

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